imall

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μ**PG2422TK**

Data Sheet

GaAs Integrated Circuit SPDT Switch for 0.05 GHz to 6.0 GHz R09DS0013EJ0100 Rev.1.00 Jan 20, 2011

DESCRIPTION

The μ PG2422TK is a GaAs MMIC SPDT (Single Pole Double Throw) switch which was designed for 0.05 GHz to 6.0 GHz applications, including dual-band wireless LAN.

This device operates with dual control switching voltages of 1.8 to 5.3 V and can operate at frequencies from 0.05 GHz to 6.0 GHz, having the low insertion loss and high isolation.

This device is housed in a 6-pin lead-less minimold package (1511 PKG) and is suitable for high-density surface mounting.

FEATURES

٠	Switch control voltage	: $V_{\text{cont (H)}} = 3.0 \text{ V TYP}.$
		: $V_{\text{cont }(L)} = 0 \text{ V TYP}.$
٠	Low insertion loss	: $L_{ins} = 0.35 \text{ dB TYP}$. @ f = 2.5 GHz
		: $L_{ins} = 0.55 \text{ dB TYP}$. @ f = 6.0 GHz
٠	High isolation	: ISL = 28 dB TYP. @ f = 2.5 GHz
		: ISL = 24 dB TYP. @ f = 6.0 GHz
٠	Handling power	: $P_{in (0.1 dB)} = +28 dBm TYP$. @ f = 2.0 to 6.0 GHz
٠	High-density surface mounting	: 6-pin lead-less minimold package $(1.5 \times 1.1 \times 0.55 \text{ mm})$

APPLICATIONS

• Wireless LAN (IEEE802.11a/b/g/n), etc.

ORDERING INFORMATION

Part Number	Order Number	Package	Marking	Supplying Form
μPG2422TK-E2	μPG2422TK-E2-A	6-pin lead-less	G6J	 Embossed tape 8 mm wide
		minimold		• Pin 1, 6 face the perforation side of the tape
		(1511 PKG)		Qty 5 kpcs/reel
		(Pb-Free)		

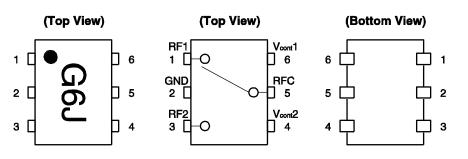
Remark To order evaluation samples, please contact your nearby sales office. Part number for sample order: μ PG2422TK-A

CAUTION

Although this device is designed to be as robust as possible, ESD (Electrostatic Discharge) can damage this device. This device must be protected at all times from ESD. Static charges may easily produce potentials of several kilovolts on the human body or equipment, which can discharge without detection. Industry-standard ESD precautions must be employed at all times.



PIN CONNECTIONS AND INTERNAL BLOCK DIAGRAM



Pin No.	Pin Name
1	RF1
2	GND
3	RF2
4	V _{cont} 2
5	RFC
6	V _{cont} 1

SW TRUTH TABLE

ON Path	V _{cont} 1	V _{cont} 2
RFC-RF1	High	Low
RFC-RF2	Low	High

ABSOLUTE MAXIMUM RATINGS (T_A = +25°C, unless otherwise specified)

Symbol	Ratings	Unit
V _{cont}	+6.0 Note	V
Pin	+29.0	dBm
Pin	+32.0	dBm
Pin	+33.0	dBm
PD	150	mW
T _A	-45 to +85	°C
T _{stg}	–55 to +150	°C
	V _{cont} P _{in} P _{in} P _D T _A	V _{cont} +6.0 Note P _{in} +29.0 P _{in} +32.0 P _{in} +33.0 P _D 150 T _A -45 to +85

Note: $|V_{cont}1 - V_{cont}2| \le 6.0 \text{ V}$

RECOMMENDED OPERATING RANGE (TA = +25°C, unless otherwise specified)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Operating Frequency	f	0.05	-	6.0	GHz
Switch Control Voltage (H)	V _{cont (H)}	1.8	3.0	5.3	V
Switch Control Voltage (L)	V _{cont (L)}	-0.2	0	0.2	V
Control Voltage Difference	$\begin{array}{c} \varDelta V_{cont \ (H)}, \\ \varDelta V_{cont \ (L)} \\ \textbf{Note} \end{array}$	-0.1	0	0.1	V

Note: $\Delta V_{\text{cont (H)}} = V_{\text{cont}} \mathbf{1}_{(\text{H})} - V_{\text{cont}} \mathbf{2}_{(\text{H})}$ $\Delta V_{\text{cont (L)}} = V_{\text{cont}} \mathbf{1}_{(\text{L})} - V_{\text{cont}} \mathbf{2}_{(\text{L})}$



ELECTRICAL CHARACTERISTICS 1

 $(T_A = +25^{\circ}C, V_{cont (H)} = 3.0 V, V_{cont (L)} = 0 V, Z_O = 50 \Omega, DC blocking capacitors = 8 pF, unless otherwise specified)$

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Insertion Loss 1	L _{ins} 1	f = 0.05 to 0.5 GHz ^{Note 1}	-	0.30	_	dB
Insertion Loss 2	L _{ins} 2	f = 0.5 to 2.0 GHz Note 2		0.30	0.50	dB
Insertion Loss 3	L _{ins} 3	f = 2.0 to 2.5 GHz		0.35	0.55	dB
Insertion Loss 4	L _{ins} 4	f = 2.5 to 3.8 GHz		0.45	0.65	dB
Insertion Loss 5	L _{ins} 5	f = 3.8 to 6.0 GHz	-	0.55	0.75	dB
Isolation 1 (RFC-OFF Port)	ISL1	f = 0.05 to 0.5 GHz ^{Note 1}		35	_	dB
Isolation 2 (RFC-OFF Port)	ISL2	f = 0.5 to 2.0 GHz Note 2	25	28	_	dB
Isolation 3 (RFC-OFF Port)	ISL3	f = 2.0 to 2.5 GHz	25	28	_	dB
Isolation 4 (RFC-OFF Port)	ISL4	f = 2.5 to 3.8 GHz	25	28	_	dB
Isolation 5 (RFC-OFF Port)	ISL5	f = 3.8 to 6.0 GHz	20	24	_	dB
Isolation 6 (RF1-RF2)	ISL6	f = 0.05 to 0.5 GHz ^{Note 1}		35	_	dB
Isolation 7 (RF1-RF2)	ISL7	f = 0.5 to 2.0 GHz Note 2	25	28	_	dB
Isolation 8 (RF1-RF2)	ISL8	f = 2.0 to 2.5 GHz	25	28	_	dB
Isolation 9 (RF1-RF2)	ISL9	f = 2.5 to 3.8 GHz	25	28	_	dB
Isolation 10 (RF1-RF2)	ISL10	f = 3.8 to 6.0 GHz	25	28	_	dB
Return Loss 1	RL1	f = 0.05 to 0.5 GHz ^{Note 1}		25	_	dB
Return Loss 2	RL2	f = 0.5 to 2.0 GHz Note 2	15	20	-	dB
Return Loss 3	RL3	f = 2.0 to 2.5 GHz	15	20	_	dB
Return Loss 4	RL4	f = 2.5 to 6.0 GHz	10	15	_	dB
0.1 dB Loss Compression	P _{in (0.1 dB)}	f = 0.05 to 0.5 GHz ^{Note 1}	-	28	_	dBm
Input Power Note 3		f = 0.5 to 2.0 GHz Note 2	-	29	-	dBm
		f = 2.0 to 6.0 GHz	-	28	-	dBm
		$f = 0.05 \text{ to } 0.5 \text{ GHz}^{\text{Note 1}}, V_{\text{cont (H)}} = 5.0 \text{ V}$	-	32	_	dBm
		$f = 0.5 \text{ to } 2.0 \text{ GHz}^{\text{Note 2}}, V_{\text{cont (H)}} = 5.0 \text{ V}$	-	32	_	dBm
		$f = 2.0 \text{ to } 6.0 \text{ GHz}, V_{\text{cont (H)}} = 5.0 \text{ V}$	-	32	-	dBm
1 dB Loss Compression	Pin (1 dB)	f = 0.05 to 0.5 GHz	_	32	_	dBm
Input Power Note 4		f = 0.5 to 2.0 GHz Note 2	-	32	_	dBm
		f = 2.0 to 6.0 GHz	-	31	_	dBm
Input 3rd Order Intercept Point	IIP ₃	f = 2.5 GHz, P _{in} = +20 dBm		57	_	dBm
2nd Harmonics	2f0	f = 2.5 GHz, P _{in} = +20 dBm		80	_	dBc
3rd Harmonics	3f0	f = 2.5 GHz, P _{in} = +20 dBm	—	80	_	dBc
Switch Control Current	I _{cont}	No RF input	_	0.1	5	μA
Switch Control Speed	t _{sw}	50% CTL to 90/10% RF	-	40	100	ns

Notes 1. DC blocking capacitors = 1 000 pF at f = 0.05 to 0.5 GHz

2. DC blocking capacitors = 56 pF at f = 0.5 to 2.0 GHz

3. P_{in (0.1 dB)} is the measured input power level when the insertion loss increases 0.1 dB more than that of the linear range.

4. P_{in (1 dB)} is the measured input power level when the insertion loss increases 1 dB more than that of the linear range.

CAUTION

It is necessary to use DC blocking capacitors with this device. The value of DC blocking capacitors should be chosen to accommodate the frequency of operation, bandwidth, switching speed and the condition with actual board of your system.



ELECTRICAL CHARACTERISTICS 2

(T_A = +25°C, V_{cont (H)} = 1.8 V, V_{cont (L)} = 0 V, Z_O = 50 Ω , DC blocking capacitors = 8 pF, unless otherwise specified)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Insertion Loss 1	L _{ins} 1	f = 0.05 to 0.5 GHz Note 1	_	0.30	_	dB
Insertion Loss 2	L _{ins} 2	f = 0.5 to 2.0 GHz Note 2	_	0.30	0.55	dB
Insertion Loss 3	L _{ins} 3	f = 2.0 to 2.5 GHz	_	0.35	0.60	dB
Insertion Loss 4	L _{ins} 4	f = 2.5 to 3.8 GHz	_	0.45	0.70	dB
Insertion Loss 5	L _{ins} 5	f = 3.8 to 6.0 GHz	_	0.55	0.80	dB
Isolation 1 (RFC-OFF Port)	ISL1	f = 0.05 to 0.5 GHz Note 1	_	35	_	dB
Isolation 2 (RFC-OFF Port)	ISL2	f = 0.5 to 2.0 GHz ^{Note 2}	24	28	_	dB
Isolation 3 (RFC-OFF Port)	ISL3	f = 2.0 to 2.5 GHz	24	28	_	dB
Isolation 4 (RFC-OFF Port)	ISL4	f = 2.5 to 3.8 GHz	24	28	_	dB
Isolation 5 (RFC-OFF Port)	ISL5	f = 3.8 to 6.0 GHz	19	24	_	dB
Isolation 6 (RF1-RF2)	ISL6	f = 0.05 to 0.5 GHz ^{Note 1}	_	35	_	dB
Isolation 7 (RF1-RF2)	ISL7	f = 0.5 to 2.0 GHz ^{Note 2}	24	28	_	dB
Isolation 8 (RF1-RF2)	ISL8	f = 2.0 to 2.5 GHz	24	28	_	dB
Isolation 9 (RF1-RF2)	ISL9	f = 2.5 to 3.8 GHz	24	28	_	dB
Isolation 10 (RF1-RF2)	ISL10	f = 3.8 to 6.0 GHz	24	28	_	dB
Return Loss 1	RL1	f = 0.05 to 0.5 GHz ^{Note 1}	_	25	_	dB
Return Loss 2	RL2	f = 0.5 to 2.0 GHz Note 2	15	20	_	dB
Return Loss 3	RL3	f = 2.0 to 2.5 GHz	15	20	_	dB
Return Loss 4	RL4	f = 2.5 to 6.0 GHz	10	15	_	dB
0.1 dB Loss Compression	P _{in (0.1 dB)}	f = 0.05 to 0.5 GHz ^{Note 1}	_	22	_	dBm
Input Power Note 3		f = 0.5 to 2.0 GHz ^{Note 2}	-	22	-	dBm
		f = 2.0 to 6.0 GHz	-	21	-	dBm
1 dB Loss Compression	Pin (1 dB)	f = 0.05 to 0.5 GHz ^{Note 1}	_	28	_	dBm
Input Power Note 4		f = 0.5 to 2.0 GHz Note 2	_	27	_	dBm
		f = 2.0 to 6.0 GHz	_	24	_	dBm
2nd Harmonics	2f0	f = 2.5 GHz, P _{in} = +15 dBm	_	80	_	dBc
3rd Harmonics	3f0	$f = 2.5 \text{ GHz}, P_{in} = +15 \text{ dBm}$	_	80	_	dBc
Switch Control Current	I _{cont}	No RF input	_	0.1	5	μA
Switch Control Speed	t _{sw}	50% CTL to 90/10% RF	_	60	150	ns

Notes 1. DC blocking capacitors = 1 000 pF at f = 0.05 to 0.5 GHz

2. DC blocking capacitors = 56 pF at f = 0.5 to 2.0 GHz

3. P_{in (0.1 dB)} is the measured input power level when the insertion loss increases 0.1 dB more than that of the linear range.

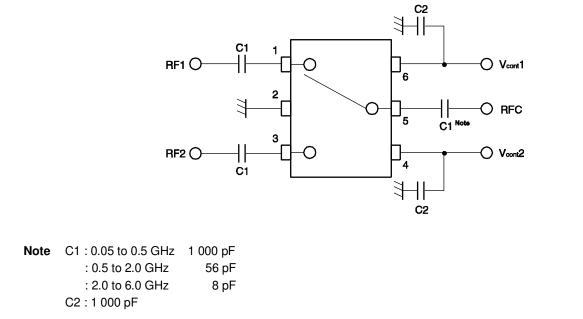
4. P_{in (1 dB)} is the measured input power level when the insertion loss increases 1 dB more than that of the linear range.

CAUTION

It is necessary to use DC blocking capacitors with this device. The value of DC blocking capacitors should be chosen to accommodate the frequency of operation, bandwidth, switching speed and the condition with actual board of your system.

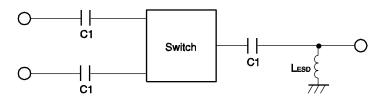


EVALUATION CIRCUIT



The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.

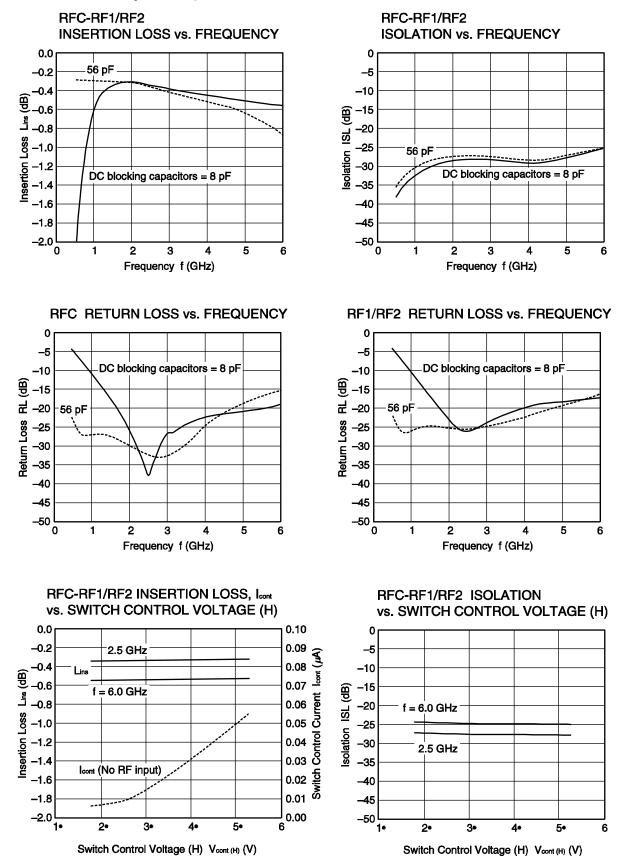
APPLICATION INFORMATION



- C1 are DC blocking capacitors external to the device. The value may be tailored to provide specific electrical responses.
- The RF ground connections should be kept as short as possible and connected to directly to a good RF ground for best performance.
- L_{ESD} provides a means to increase the ESD protection on a specific RF port, typically the port attached to the antenna.



 $(T_A = +25^{\circ}C, V_{cont (H)} = 3.0 V, V_{cont (L)} = 0 V, Z_O = 50 \Omega, DC blocking capacitors = 8 pF, unless otherwise specified)$



Remark The graphs indicate nominal characteristics.



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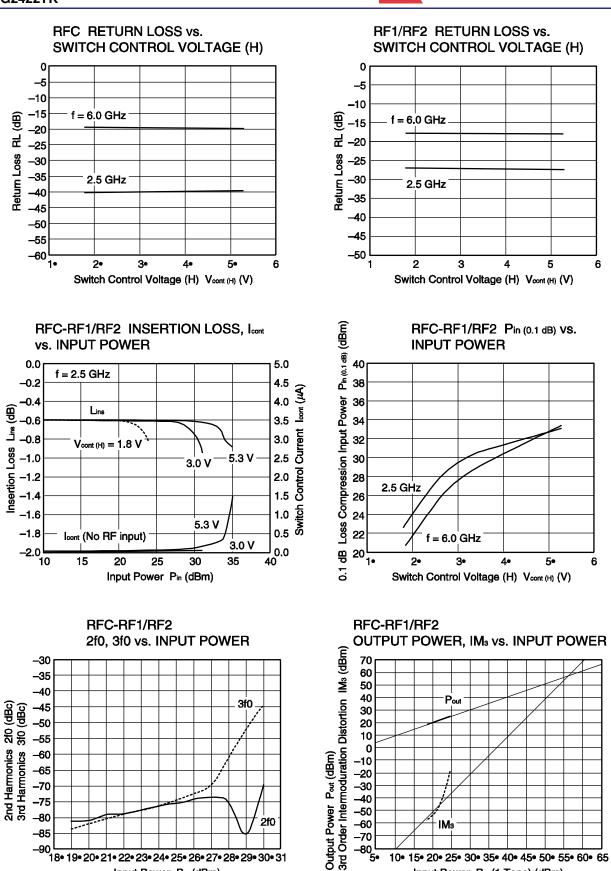
Return Loss

<u>B</u>

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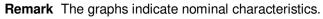
Loss

Insertion



, 18• 19• 20• 21• 22• 23• 24• 25• 26• 27• 28• 29• 30• 31

Input Power Pin (dBm)



-80

-85

-90





-60

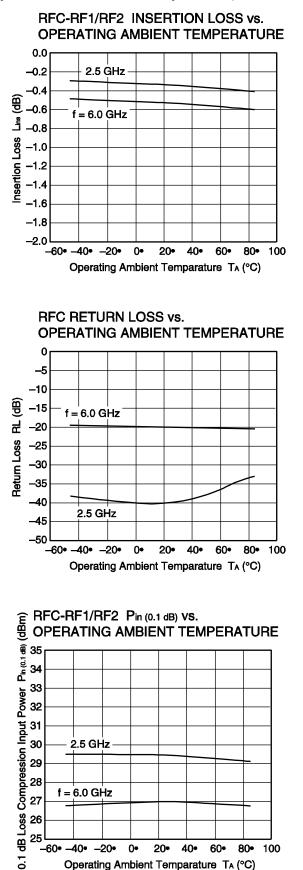
-70 -80 L 5• IMa

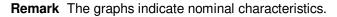
10• 15• 20• 25• 30• 35• 40• 45• 50• 55• 60• 65

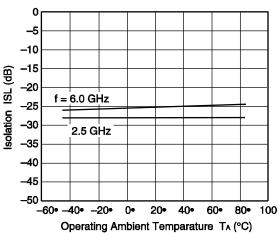
Input Power Pin (1 Tone) (dBm)

2f0

 $(T_A = -45 \text{ to } +85^{\circ}\text{C}, V_{\text{cont}(H)} = 3.0 \text{ V}, V_{\text{cont}(L)} = 0 \text{ V}, Z_0 = 50 \Omega, \text{ DC blocking capacitors} = 8 \text{ pF, unless otherwise specified})$

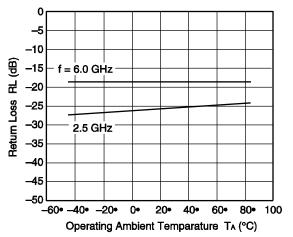




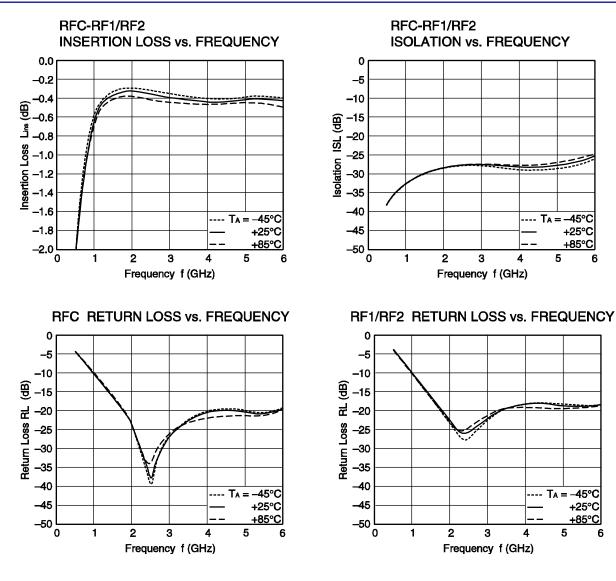


RFC-RF1/RF2 ISOLATION vs. OPERATING AMBIENT TEMPERATURE

RF1/RF2 RETURN LOSS vs. OPERATING AMBIENT TEMPERATURE



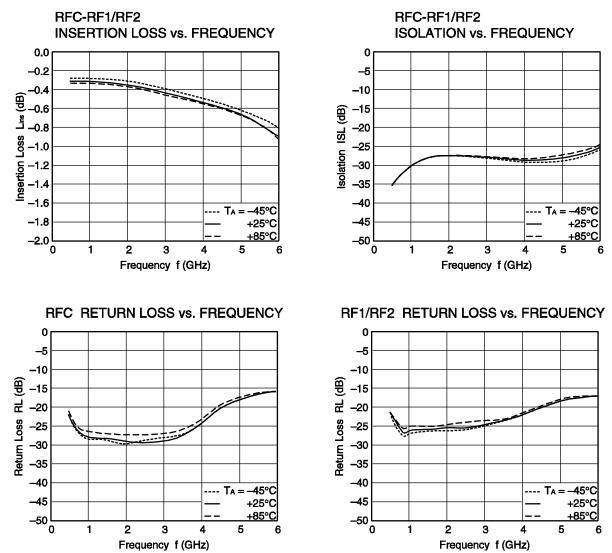




Remark The graphs indicate nominal characteristics.



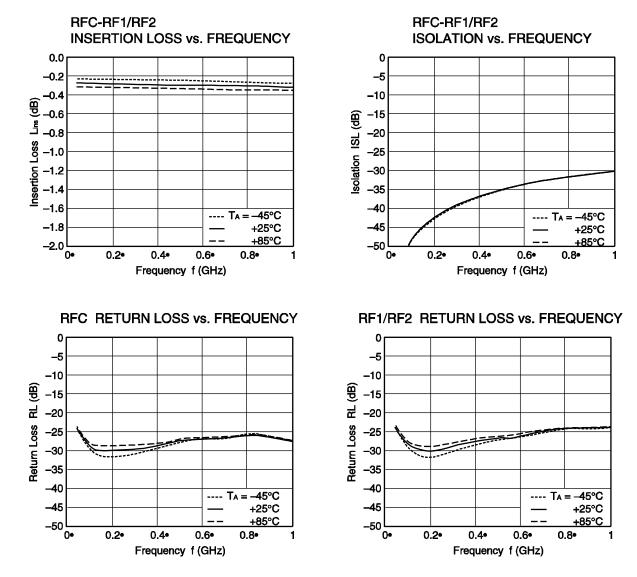
(V_{cont (H)} = 3.0 V, V_{cont (L)} = 0 V, Z₀ = 50 Ω , DC blocking capacitors = 56 pF, unless otherwise specified)



Remark The graphs indicate nominal characteristics.



 $(V_{cont~(H)}$ = 3.0 V, $V_{cont~(L)}$ = 0 V, Z_{O} = 50 $\Omega,$ DC blocking capacitors = 1 000 pF, unless otherwise specified)

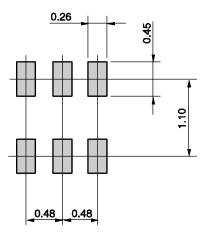


Remark The graphs indicate nominal characteristics.



MOUNTING PAD LAYOUT DIMENSIONS

6-PIN LEAD-LESS MINIMOLD (1511 PKG) (UNIT: mm)

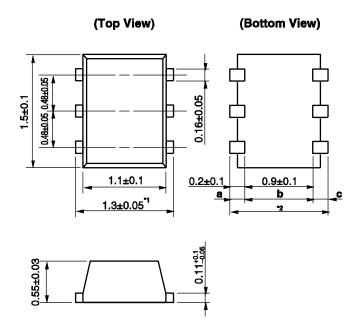


Remark The mounting pad layout in this document is for reference only.



PACKAGE DIMENSIONS

6-PIN LEAD-LESS MINIMOLD (1511 PKG) (UNIT: mm)



Remark Dimension¹ is bigger than dimension² (dimension² = $\mathbf{a} + \mathbf{b} + \mathbf{c}$).



RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions		Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature)	: 260°C or below	IR260
	Time at peak temperature	: 10 seconds or less	
	Time at temperature of 220°C or higher	: 60 seconds or less	
	Preheating time at 120 to 180°C	: 120±30 seconds	
	Maximum number of reflow processes	: 3 times	
	Maximum chlorine content of rosin flux (% mass)	: 0.2%(Wt.) or below	
Wave Soldering	Peak temperature (molten solder temperature)	: 260°C or below	WS260
	Time at peak temperature	: 10 seconds or less	
	Preheating temperature (package surface temperature): 120°C or below	
	Maximum number of flow processes	: 1 time	
	Maximum chlorine content of rosin flux (% mass)	: 0.2%(Wt.) or below	
Partial Heating	Peak temperature (terminal temperature)	: 350°C or below	HS350
	Soldering time (per side of device)	: 3 seconds or less	
	Maximum chlorine content of rosin flux (% mass)	: 0.2%(Wt.) or below	

CAUTION

Do not use different soldering methods together (except for partial heating).



μ**PG2422TK**

Caution GaAs Products	This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.
	• Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
	 Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
	Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
	Do not burn, destroy, cut, crush, or chemically dissolve the product.
	Do not lick the product or in any way allow it to enter the mouth.



Revision H	istory
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μ PG2422TK Data Sheet

		Description	
Rev.	Date	Page	Summary
1.00	Jan 20, 2011	-	First edition issued